

FCDN608-UBM

1-Channel ESD Protector

Product Description

The FCDN608-UBM provides robust ESD protection for sensitive parts that may be subjected to electrostatic discharge (ESD). The tiny form factor and single pad allows it to be used in very confined spaces. The electrical 'back-to-back zener' configuration provides symmetrical ESD protection in cases where nodes with AC signals are present. This device is designed and characterized to safely dissipate ESD strikes of at least ± 15 kV, according to the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD.

Features

- Compact Die Protects from ESD Discharges
- Almost No Conduction at Signal Amplitudes Less than ± 5 V
- ESD Protection to over ± 15 kV (Human Body Model HBM) per MIL_STD_883 International ESD Standard

Applications

- LED Lighting
- Modules
- Interface Circuits



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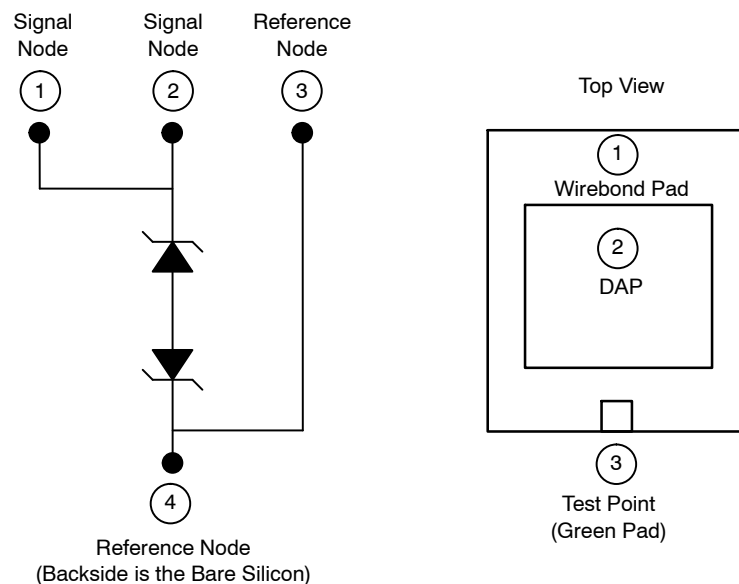


Figure 1. Electrical Schematic and Top View

ORDERING INFORMATION

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

FCDN608-UBM

Table 1. PIN DESCRIPTIONS

FCDN608-UBM (Schematic and Top View)			
Designation	Schematic	Top View	Metal Composition
1	Signal Node	Wirebond Pad	Al
2	Signal Node	DAP	Cu
3	Reference Node	Test Point	-
4	Reference Node	N/A	Bare Silicon

Table 2. ORDERING INFORMATION

Ordering Part Number	DAP (Die Attach Pad)	Backside Metal	BG Thickness	Shipping Method
FCDN608-UBM	Cu (Copper)	Bare Silicon	10 mils	Wafer Form

SPECIFICATIONS

Table 3. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Operating Junction Temperature Range	-40 to +150	°C
Storage Junction Temperature Range	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Junction Temperature Range	-40 to +150	°C

Table 5. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{LEAK}	Leakage Current	$V = \pm 5\text{ V}, 25^\circ\text{C}$ $V = -10\text{ V}, 25^\circ\text{C}$ $V = \pm 5\text{ V}, 150^\circ\text{C}$			+0.35 -0.35 4.0	μA μA mA
V_{CL}	Clamp Voltage on Signal Node Positive Polarity Negative Polarity	$T_A = 25^\circ\text{C}$ at 10 mA at -10 mA	+5 -14	+7 -11.5	+9 -10	V
V_{ESD}	ESD Protection – Withstand Voltage: Human Body Model (MIL-STD-883, Method 3015)	$T_A = 25^\circ\text{C}$	± 15			kV
V_{CL_ESD}	Clamping Voltage on Signal Node for Transients Positive Polarity Negative Polarity	$I_{PP} = 1\text{ A}, t_p = 8/20\ \mu\text{s}$ Positive Transients Negative Transients		+7 -12		V
R_{DYN}	Dynamic Resistance R_{DYN+} R_{DYN-}	$I_{PP} = 1\text{ A}, t_p = 8/20\ \mu\text{s}$ Positive Transients Negative Transients		0.2 0.4		Ω
C_{IN}	Input Capacitance	At 1 MHz, 30 mV osc. Level, 0 VDC Bias (Note 2) At 1 MHz, 30 mV osc. Level, 3 VDC Bias		175 120		pF

1. Operating characteristics are over standard operating conditions unless otherwise specified.

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MECHANICAL DETAILS

Table 6. MECHANICAL SPECIFICATIONS

Parameter	Condition	Units
Composition	Silicon Wafer, n+ Doped	
Die Shape	Rectangular	
Length (Stepping Size)	1560	μm
Width (Stepping Size)	1160	μm
BG Thickness	10	mils
Saw Street Widths (Space between Devices on Wafer) (Note 1)	40 (X-Direction) 40 (Y-Direction)	μm
Die Attach Pad Length	1000	μm
Die Attach Pad Width	1000	μm
Die Attach Pad (DAP)	Cu (Copper)	
Backside Metal	Bare Silicon	

1. The saw street is defined as the passivation-free area between devices.

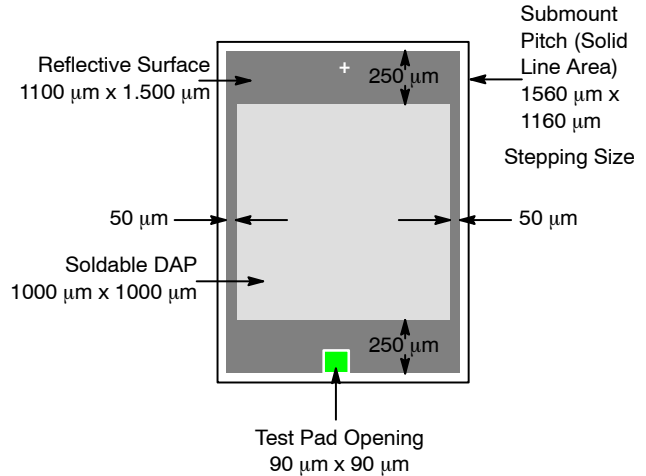


Figure 2. Die Dimensions

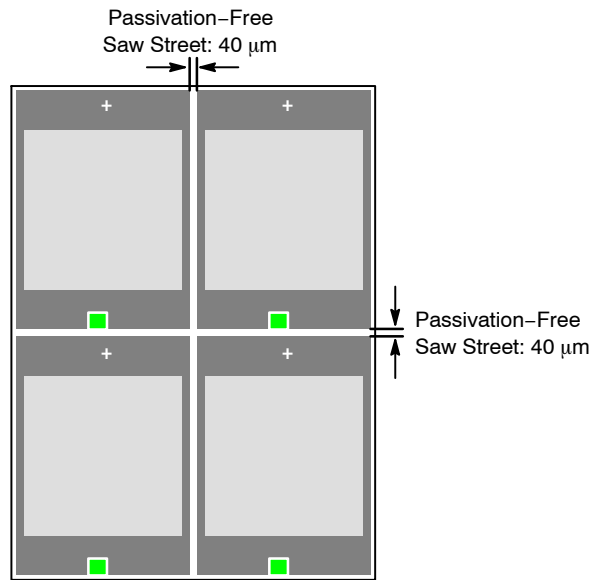


Figure 3. Die-Array on Wafer

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